



In re Application of:  
Sun, et al.

Confirmation No.: 1645

Filed: July 8, 2003

# For: Multiple-Step Electrodeposition Process for Direct Copper Plating on Barrier Metals

2025

Group Art Unit: 1753

Examiner: Edna Wong

**MAIL STOP AMENDMENT**  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

## 37 CFR 1.8

I hereby certify that this correspondence is being deposited on September 8, 2005 with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

September 8, 2005  
Date

Signature \_\_\_\_\_

Dear Sir:

**RESPONSE TO OFFICE ACTION DATED JUNE 8, 2005**

In response to the Office Action dated June 8, 2005, having a shortened statutory period for response set to expire on September 8, 2005, please enter this response and reconsider the claims pending in the application for reasons discussed below. Although Applicant believes that no additional fees are due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/APPM/008241/KMT, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

**Amendments to the Claims** begin on page 2 of this paper. **Remarks** begin on page 8 of this paper.